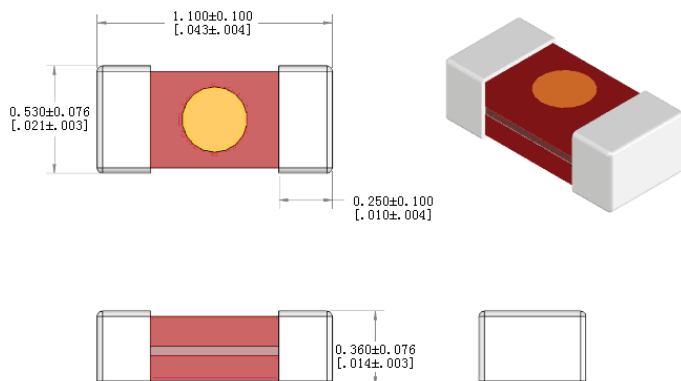
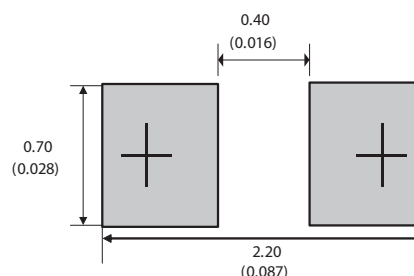


Dimensions - mm (in)



Recommended Pad Layout - mm (in)

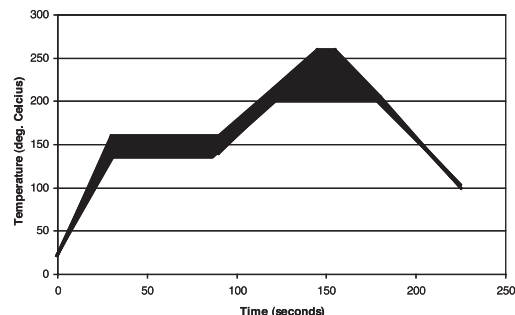


Environmental Specifications:

- High Temperature Exposure: MIL-STD-202 Method 108
- Temperature Cycling: 1000 Air to Air cycles -40°C to $+125^{\circ}\text{C}$ JESD22 Method JA-104
- Moisture Resistance Test: MIL-STD-202 Method 106G, 10 cycles
- Biased Humidity: MIL-STD-202 Method 103, 1,000 hours $+85^{\circ}\text{C}$, 85%RH
- Thermal Shock: MIL-STD-202, Method 107G Air-to-Air -55°C to $+125^{\circ}\text{C}$, 10 cycles
- Vibration Test and Mechanical Shock Test: MIL-STD-202 Method 204 and Method 213
- Resistance to Solvent: MIL-STD-202 Method 215
- Operating and Storage Temperature Range: -55°C to $+125^{\circ}\text{C}$

Soldering Recommendations

- Compatible with lead and lead-free solder reflow processes
- Peak reflow temperatures and durations:
 - IR Reflow = 260°C max for 10 sec. max
 - Wave Solder = 260°C max. for 10 sec. max
- Recommended IR Reflow Profile:



Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

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